


# PRODUCT / PROCESS CHANGE NOTIFICATION

## 1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	ANALOG MEMS SENSORS/25/15575
1.3 Title of PCN	ST Manufacturing Reshaping (Analog_Adv BCD9_AG200toAG300_All): Qualification of AG300 (Italy) as new FE Location.
1.4 Product Category	Please refer to the Impacted Products list in BCD9
1.5 Issue date	2025-07-28

## 2. PCN Team

2.1 Contact supplier	
2.1.1 Name	KRISZTINA NEMETH
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Domenico ARRIGO, Marcello SAN BIAGIO
2.1.2 Marketing Manager	Fabio CHELLI, Vito GRAZIANO, Salvatore DI VINCENZO
2.1.3 Quality Manager	Alessandro PLATINI, Daniela FAZIO

## 3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Manufacturing reshaping program	Manufacturing reshaping program	AG300 (Italy) as Front End Plant.

## 4. Description of change

	Old	New
4.1 Description	AG200 (Italy) ad Front End Plant.	AG300 (Italy) ad Front End Plant.
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No Impact. The products guarantee the same quality and electrical characteristics as per current production.	

## 5. Reason / motivation for change

5.1 Motivation	In the frame of ST manufacturing reshaping program (refer to Corporate PCI 15383 - Early Notification), following the continuous improvement of our service and to increase production Capacity, ST Microelectronics is announcing the qualification of AG300 (Italy) as FE Location for the impacted Products in BCD9 Technology. Please note that on top of Front end transfer, we will implement a change in a component of glue ablestick 8601-S25 to become PFAS free on selected products. Please be advised that the enclosed list of products and dates could be subject to change. Such modifications may occur as part of the ongoing transformation program and will be communicated as and when available.
5.2 Customer Benefit	SERVICE CONTINUITY

## 6. Marking of parts / traceability of change

6.1 Description	Traceability of change will be ensured by an internal codification (Finished Good/Type) printed on the carton box label.
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## 7. Timing / schedule

7.1 Date of qualification results	2026-12-15
7.2 Intended start of delivery	2027-06-15
7.3 Qualification sample available?	Upon Request

## 8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)
15575 Public product.pdf 15575 Qualification Plan Detail_adv BCD9.zip

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	L9370TR	
	L9908TR	
	L9961TR	
	L9963T-TR	
	L9965P-FN-TR	
	L9966CB-TR	
	L99BM1T-TR	
	SPSB0815-TR	
	STPM802-TR	
	L9963T	
	L9965P-FN	

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